

L Number	Hits	Search Text	DB	Time stamp
8	593	('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)	USPAT;	2003/09/09 07:45
9	587	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3	US-PGPUB; EPO; JPO	2003/09/09 07:40
10	587	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:41
11	208	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:41
12	207	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:42
13	128	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:58
14	54	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry) and (slurry with dispersion)	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:42
15	53	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry) and (slurry with dispersion)) and ( "CMP" "(CMP)")	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:45
19	62	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and (polishing adj slurry with silica)	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:59
20	38	((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry) and (slurry with dispersion)) and ( "CMP" "(CMP)") and (polishing adj slurry with silica)	USPAT; US-PGPUB; EPO; JPO	2003/09/09 07:59
21	1		USPAT	2003/09/09 08:03